

## Product Advisory (PA)

**Subject:** Package Outline Correction for 8L / SOIC-EP

**Publication Date:** 8/9/2019

**Effective Date:** 8/9/2019

**Revision Description:**

Initial Release

**Description of Change:**

This notice is to you that Renesas Electronics America Inc has updated 8 leads EPSOIC (Exposed Pad Small Outline Integrated Circuit). The updates include changes to the following:

### 8L / SOIC - Exposed Pad (150mil)

Package Outline Description	Symbol	From		To		From		To	
		Min (inch)	Max (inch)	Min (inch)	Max (inch)	Min (mm)	Max (mm)	Min (mm)	Max (mm)
Package Total Height	A	0.056"	0.066"	0.056"	<b>0.067"</b>	1.430	1.680	<b>1.422</b>	<b>1.700</b>
Package Standoff height	A1	0.001"	0.005"	<b>0.0"</b>	0.005"	0.030	0.130	<b>0.000</b>	0.130
Foot Length	L	0.016"	0.035"	0.016"	0.035"	0.410	0.890	<b>0.406</b>	0.890

❖ **RED** font indicated the dimension change in inches and millimeters.

### Affected Product List

ISL6613AEIBZ	ISL78307FBEBZ-T	ISL78307FBECZTKR5632	ISL80410IBEZ-T7A	ISL6506ACBZ-T
ISL6613AEIBZ-T	ISL78307FBEBZ-T7A	ISL80136IBEAJZ	HIP2100EIBZ	ISL6506BCBZ
ISL78307FBEAZ	ISL78307FBEBZ-TR5506	ISL80136IBEAJZ-T	HIP2100EIBZT	ISL6506BCBZ-T
ISL78307FBEAZ-T	ISL78307FBECZ	ISL80136IBEAJZ-T7A	HIP2101EIBZ	ISL6506BCBZ-TR5418
ISL78307FBEAZ-T7A	ISL78307FBECZ-T	ISL80136IBEAJZTR5632	HIP2101EIBZ-TS2705	ISL6506BCBZA
ISL78307FBEAZ-TR5506	ISL78307FBECZ-T7A	ISL80410IBEZ	HIP2101EIBZT	ISL6506BCBZA-T
ISL78307FBEBZ	ISL78307FBECZ-TR5303	ISL80410IBEZ-T	ISL6506ACBZ	ISL6506BCBZA-TS2568

**Reason for Change:**

The correction to the package outline aligns the documentation with the product characteristics.

**Impact on fit, form, function, quality & reliability:**

This is minor package dimension update. The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

**Product Identification:**

Product affected by this change is identifiable via Renesas's internal traceability system.

**Qualification status:** Not Applicable

**Sample availability:** 8/9/2019

**Device material declaration:** Available upon request

*Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.*

For additional information regarding this notice, please contact your regional change coordinator (below)

Americas: <a href="mailto:PCN-US@RENESAS.COM">PCN-US@RENESAS.COM</a>	Europe: <a href="mailto:PCN-EU@RENESAS.COM">PCN-EU@RENESAS.COM</a>	Japan: <a href="mailto:PCN-JP@RENESAS.COM">PCN-JP@RENESAS.COM</a>	Asia Pac: <a href="mailto:PCN-APAC@RENESAS.COM">PCN-APAC@RENESAS.COM</a>
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Appendix A – Package Outline Drawing (POD) 8 Leads / SOIC – Exposed Pad

